

16 Mbit (2Mb x8 or 1Mb x16) Low Voltage UV EPROM and OTP EPROM

- LOW VOLTAGE READ OPERATION: 3V to 3.6V
- FASTACCESS TIME: 100ns
 BYTE-WIDE or WORD-WIDE CONFIGURABLE
- 16 Mbit MASK ROM REPLACEMENT
- LOW POWER CONSUMPTION
 - Active Current 30mA at 8MHz
 - Standby Current 20μA
- PROGRAMMING VOLTAGE: 12.5V ± 0.25V
 PROGRAMMING TIME: 100µs/byte (typical)
- ELECTRONIC SIGNATUREManufacturer Code: 0020hDevice Code: 00B1h

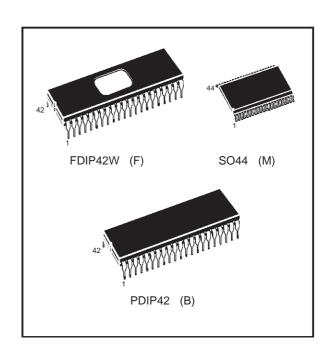
DESCRIPTION

The M27V160 is a low voltage 16 Mbit EPROM offered in the two ranges UV (ultra violet erase) and OTP (one time programmable). It is ideally suited for microprocessor systems requiring large data or program storage. It is organised as either 2 Mbit words of 8 bit or 1 Mbit words of 16 bit. The pin-out is compatible with a 16 Mbit Mask ROM.

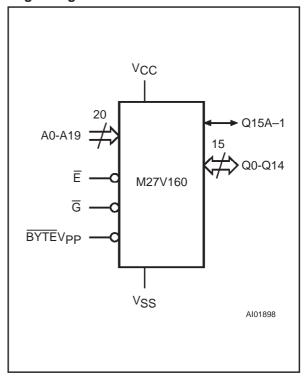
The M27V160 operates in the read mode with a supply voltage as low as 3V. The decrease in operating power allows either a reduction of the size of the battery or an increase in the time between battery recharges.

Table 1. Signal Names

A0-A19	Address Inputs
Q0-Q7	Data Outputs
Q8-Q14	Data Outputs
Q15A-1	Data Output / Address Input
Ē	Chip Enable
G	Output Enable
BYTEV _{PP}	Byte Mode / Program Supply
V _{CC}	Supply Voltage
Vss	Ground



Logic Diagram



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Figure 2A. DIP Pin Connections

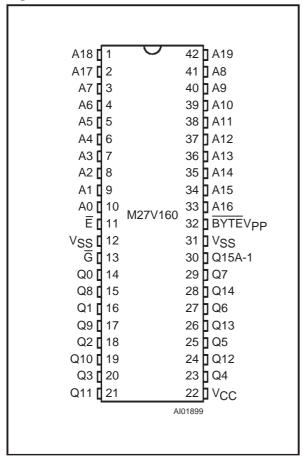
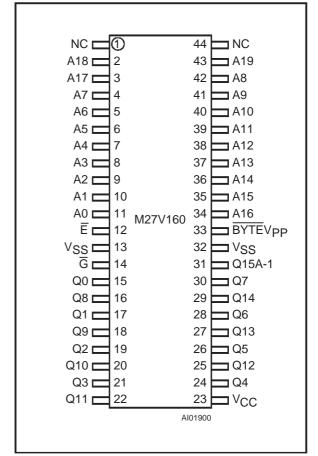


Figure 2B. SO Pin Connections



Warning: NC = Not Connected.

Table 2. Absolute Maximum Ratings (1)

Symbol	Parameter	Value	Unit
T _A	Ambient Operating Temperature (3)	-40 to 125	°C
T _{BIAS}	Temperature Under Bias	-50 to 125	°C
T _{STG}	Storage Temperature	-65 to 150	°C
V _{IO} (2)	Input or Output Voltages (except A9)	–2 to 7	V
V _{CC}	Supply Voltage	–2 to 7	V
V _{A9} ⁽²⁾	A9 Voltage	-2 to 13.5	V
V _{PP}	Program Supply Voltage	–2 to 14	V

Notes: 1. Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

3. Depends on range.

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^{2.} Minimum DC voltage on Input or Output is -0.5V with possible undershoot to -2.0V for a period less than 20ns. Maximum DC voltage on Output is V_{CC} +0.5V with possible overshoot to V_{CC} +2V for a period less than 20ns.

Table 3. Operating Modes

Mode	Ē	G	BYTEV _{PP}	A9	Q0 - Q7	Q8 - Q14	Q15A-1
Read Word-wide	V_{IL}	V _{IL}	V _{IH}	Х	Data Out	Data Out	Data Out
Read Byte-wide Upper	V_{IL}	V _{IL}	V_{IL}	Х	Data Out	Hi-Z	V_{IH}
Read Byte-wide Lower	V_{IL}	V _{IL}	V_{IL}	Х	Data Out	Hi-Z	V_{IL}
Output Disable	V _{IL}	V _{IH}	Х	Х	Hi-Z	Hi-Z	Hi-Z
Program	V _{IL} Pulse	V _{IH}	V_{PP}	Х	Data In	Data In	Data In
Verify	V_{IH}	V _{IL}	V_{PP}	Х	Data Out	Data Out	Data Out
Program Inhibit	V _{IH}	V _{IH}	V_{PP}	Х	Hi-Z	Hi-Z	Hi-Z
Standby	V _{IH}	Х	Х	Х	Hi-Z	Hi-Z	Hi-Z
Electronic Signature	V _{IL}	V _{IL}	V _{IH}	V _{ID}	Codes	Codes	Code

Note: $X = V_{IH}$ or V_{IL} , $V_{ID} = 12V \pm 0.5V$.

Table 4. Electronic Signature

Identifier	Α0	Q7	Q6	Q5	Q4	Q3	Q2	Q1	Q0	Hex Data
Manufacturer's Code	V _{IL}	0	0	1	0	0	0	0	0	20h
Device Code	V _{IH}	1	0	1	1	0	0	0	1	B1h

Note: Outputs Q8-Q15 are set to '0'.

DESCRIPTION (cont'd)

The FDIP42W (window ceramic frit-seal package) has a transparent lid which allows the user to expose the chip to ultraviolet light to erase the bit pattern. A new pattern can then be written rapidly to the device by following the programming procedure.

For applications where the content is programmed only one time and erasure is not required, the M27V160 is offered in PDIP42 and SO44 packages.

DEVICE OPERATION

The operating modes of the M27V160 are listed in the Operating Modes Table. A single power supply is required in the read mode. All inputs are TTL compatible except for V_{PP} and 12V on A9 for the Electronic Signature.

Read Mode

The M27V160 has two organisations, Word-wide and Byte-wide. The organisation is selected by the signal level on the BYTEV_{PP} pin. When BYTEV_{PP}

is at V_{IH} the Word-wide organisation is selected and the Q15A–1 pin is used for Q15 Data Output. When the $\overline{BYTE}V_{PP}$ pin is at V_{IL} the Byte-wide organisation is selected and the Q15A–1 pin is used for the Address Input A–1. When the memory is logically regarded as 16 bit wide, but read in the Byte-wide organisation, then with A–1 at V_{IL} the lower 8 bits of the 16 bit data are selected and with A–1 at V_{IH} the upper 8 bits of the 16 bit data are selected.

The M27V160 has two control functions, both of which must be logically active in order to obtain data at the outputs. In addition the Word-wide or Byte- wide organisation must be selected.

Chip Enable (\overline{E}) is the power control and should be used for device selection. Output Enable (\overline{G}) is the output control and should be used to gate data to the output pins independent of device selection. Assuming that the addresses are stable, the address access time (t_{AVQV}) is equal to the delay from \overline{E} to output (t_{ELQV}). Data is available at the output after a delay of t_{GLQV} from the falling edge of \overline{G} , assuming that \overline{E} has been low and the addresses have been stable for at least t_{AVQV} - t_{GLQV} .

Table 5. AC Measurement Conditions

	High Speed	Standard
Input Rise and Fall Times	≤ 10ns	≤ 20ns
Input Pulse Voltages	0 to 3V	0.4V to 2.4V
Input and Output Timing Ref. Voltages	1.5V	0.8V and 2V

Figure 3. AC Testing Input Output Waveform

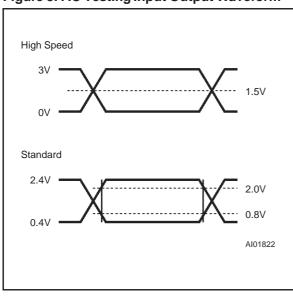


Figure 4. AC Testing Load Circuit

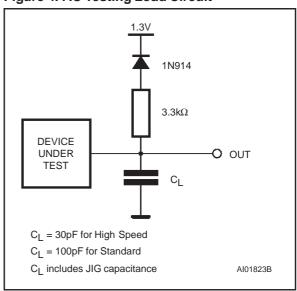


Table 6. Capacitance $^{(1)}$ (T_A = 25 °C, f = 1 MHz)

Symbol	Parameter	Test Condition	Min	Max	Unit
C _{IN}	Input Capacitance (except BYTEV _{PP})	$V_{IN} = 0V$		10	pF
OIN	Input Capacitance (BYTEV _{PP})	$V_{IN} = 0V$		120	pF
Соит	Output Capacitance	V _{OUT} = 0V		12	pF

Note: 1. Sampled only, not 100% tested.

Standby Mode

The M27V160 has a standby mode which reduces the active current from 20mA to $20\mu A$ with low voltage operation $V_{CC} \leq 3.6V$, see Read Mode DC Characteristics table for details. The M27V160 is placed in the standby mode by applying a CMOS high signal to the \overline{E} input. When in the standby mode, the outputs are in a high impedance state, independent of the \overline{G} input.

Two Line Output Control

Because EPROMs are usually used in larger memory arrays, this product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

- a. the lowest possible memory power dissipation,
- b. complete assurance that output bus contention will not occur.

Table 7. Read Mode DC Characteristics (1)

 $(T_A = 0 \text{ to } 70 \text{ °C}; V_{CC} = 3.3V \pm 10\%; V_{PP} = V_{CC})$

Symbol	Parameter	Test Condition	Min	Max	Unit
I _{LI}	Input Leakage Current	OV V _{IN} V _{CC}		±1	μА
I _{LO}	Output Leakage Current	0V V _{OUT} V _{CC}		±10	μΑ
Icc	Supply Current	$\overline{E} = V_{IL}, \overline{G} = V_{IL}, I_{OUT} = 0 mA, \\ f = 8 MHz, V_{CC} \le 3.6 V$		30	mA
icc	Supply Current $\overline{\overline{E}} = V_{IL}, \overline{\overline{G}} = V_{IL}, I_{OUT} = 0 \text{mA}$ $f = 5 \text{MHz}, V_{CC} \le 3.6 \text{V}$			20	mA
I _{CC1}	Supply Current (Standby) TTL	E = V _{IH}		1	mA
I _{CC2}	Supply Current (Standby) CMOS	\overline{E} > V _{CC} - 0.2V, V _{CC} \leq 3.6V		20	μА
I _{PP}	Program Current	$V_{PP} = V_{CC}$		10	μΑ
V _{IL}	Input Low Voltage		-0.3	0.8	V
V _{IH} ⁽²⁾	Input High Voltage		2	V _{CC} + 1	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output High Voltage TTL	I _{OH} = -400μA	2.4		V

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

2. Maximum DC voltage on Output is V_{CC} +0.5V.

For the most efficient use of these two control lines, E should be decoded and used as the primary device selecting function, while G should be made a common connection to all devices in the array and connected to the READ line from the system control bus. This ensures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is required from a particular memory device.

System Considerations

The power switching characteristics of Advanced CMOS EPROMs require carefull decoupling of the supplies to the devices. The supply current I_{CC} has three segments of importance to the system designer: the standby current, the active current and the transient peaks that are produced by the falling and rising edges of \overline{E} .

The magnitude of the transient current peaks is dependanton the capacititive and inductive loading of the device outputs. The associated transient voltage peaks can be supressed by complying with the two line output control and by properly selected decoupling capacitors. It is recommended that a 0.1µF ceramic capacitor is used on every device between V_{CC} and V_{SS}. This should be a high frequency type of low inherent inductance and should be placed as close as possible to the device. In addition, a 4.7µF electrolytic capacitor should be used between V_{CC} and V_{SS} for every eight devices. This capacitor should be mounted near the power supply connection point. The purpose of this capacitor is to overcome the voltage drop caused by the inductive effects of PCB traces.

Table 8. Read Mode AC Characteristics (1)

(T_A = 0 to 70 °C; V_{CC} = 3.3V \pm 10%; V_{PP} = V_{CC})

						M27	V160			
Symbol	Alt	Parameter	Test Condition	-10	0 ⁽³⁾	-12	0 ⁽³⁾	-1	50	Unit
				Min	Max	Min	Max	Min	Max	
t _{AVQV}	t _{ACC}	Address Valid to Output Valid	$\overline{E} = V_{IL}, \overline{G} = V_{IL}$		100		120		150	ns
t _{BHQV}	t _{ST}	BYTE High to Output Valid	$\overline{E} = V_{IL}, \overline{G} = V_{IL}$		100		120		150	ns
t _{ELQV}	t _{CE}	Chip Enable Low to Output Valid	$\overline{G} = V_{IL}$		100		120		150	ns
t _{GLQV}	t _{OE}	Output Enable Low to Output Valid	$\overline{E} = V_{IL}$		50		60		60	ns
t _{BLQZ} (2)	t _{STD}	BYTE Low to Output Hi-Z	$\overline{E} = V_{IL}, \overline{G} = V_{IL}$		45		50		50	ns
t _{EHQZ} (2)	t _{DF}	Chip Enable High to Output Hi-Z	$\overline{G} = V_{IL}$	0	45	0	50	0	50	ns
t _{GHQZ} (2)	t _{DF}	Output Enable High to Output Hi-Z	E = V _{IL}	0	45	0	50	0	50	ns
t _{AXQX}	t _{OH}	Address Transition to Output Transition	$\overline{E} = V_{IL}, \overline{G} = V_{IL}$	5		5		5		ns
t _{BLQX}	t _{OH}	BYTE Low to Output Transition	$\overline{E} = V_{IL}, \overline{G} = V_{IL}$	5		5		5		ns

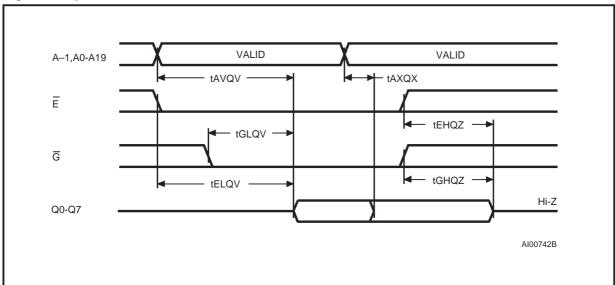
Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.
2. Sampled only, not 100% tested.
3. Speed obtained with High Speed measurement conditions.

VALID VALID A0-A19 tAVQV -- tAXQX Ē - tEHQZ -- tGLQV -G tGHQZ tELQV · Hi-Z Q0-Q15 AI00741B

Figure 5. Word-Wide Read Mode AC Waveforms

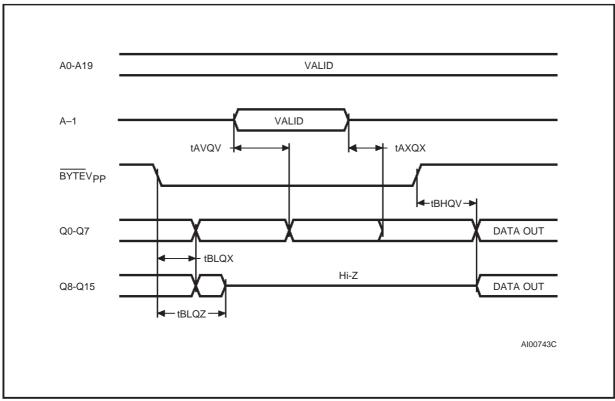
Note: $\overline{BYTE}V_{PP} = V_{IH}$.

Figure 6. Byte-Wide Read Mode AC Waveforms



Note: $\overline{BYTE}V_{PP} = V_{IL}$.

Figure 7. BYTE Transition AC Waveforms



Note: Chip Enable (\overline{E}) and Output Enable $(\overline{G}) = V_{IL}$.

Table 9. Programming Mode DC Characteristics (1)

 $(T_A = 25 \, ^{\circ}C; V_{CC} = 6.25V \pm 0.25V; V_{PP} = 12.5V \pm 0.25V)$

Symbol	Parameter	Test Condition	Min	Max	Unit
ILI	Input Leakage Current	$0 \le V_{IN} \le V_{CC}$		±1	μΑ
Icc	Supply Current			50	mA
I _{PP}	Program Current	$\overline{E} = V_{IL}$		50	mA
V _{IL}	Input Low Voltage		-0.3	0.8	V
V _{IH}	Input High Voltage		2.4	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output High Voltage TTL	$I_{OH} = -2.5 \text{mA}$	3.5		V
V _{ID}	A9 Voltage		11.5	12.5	V

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

Table 10. Programming Mode AC Characteristics (1)

 $(T_A = 25 \, ^{\circ}C; V_{CC} = 6.25V \pm 0.25V; V_{PP} = 12.5V \pm 0.25V)$

Symbol	Alt	Parameter	Test Condition	Min	Max	Unit
t _{AVEL}	t _{AS}	Address Valid to Chip Enable Low		2		μs
t _{QVEL}	t _{DS}	Input Valid to Chip Enable Low		2		μs
tvphav	t _{VPS}	V _{PP} High to Address Valid		2		μs
t _{VCHAV}	t _{VCS}	V _{CC} High to Address Valid		2		μs
t _{ELEH}	t _{PW}	Chip Enable Program Pulse Width		45	55	μs
t _{EHQX}	t _{DH}	Chip Enable High to Input Transition		2		μs
t _{QXGL}	t _{OES}	Input Transition to Output Enable Low		2		μs
t _{GLQV}	t _{OE}	Output Enable Low to Output Valid			120	ns
t _{GHQZ} (2)	t _{DFP}	Output Enable High to Output Hi-Z		0	130	ns
tghax	t _{AH}	Output Enable High to Address Transition		0		ns

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}. 2. Sampled only, not 100% tested.

Programming

The M27V160 has been designed to be fully compatible with the M27C160. As a result the M27V160 can be programmed as the M27C160 on the same programming equipments applying 12.75V on VPP and 6.25 V on V_{CC} by the use of the same PRESTO III algorithm. When delivered (and after each erasure for UV EPROM), all bits of the M27V160 are in the '1' state. Data is introduced by selectively programming '0's to the desired bit locations. Al-

though only '0's will be programmed, both '1's and '0's can be present in the data word. The only way to change a '0' to a '1' is by die exposition to ultraviolet light (UV EPROM). The M27V160 is in the programming mode when V_{pp} input is at 12.5V, \overline{G} is at V_{IH} and \overline{E} is pulsed to V_{IL} . The data to be programmed is applied to 16 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL. V_{CC} is specified to be $6.25V \pm 0.25V$.

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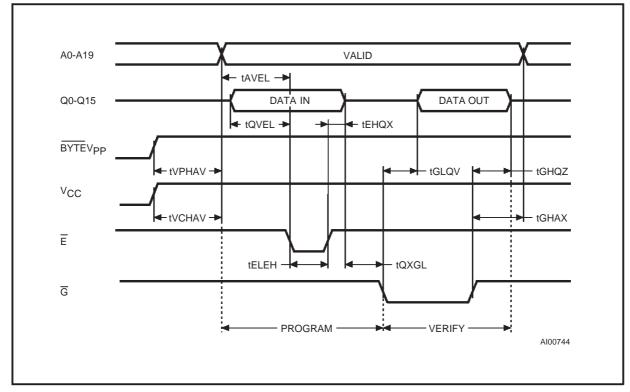
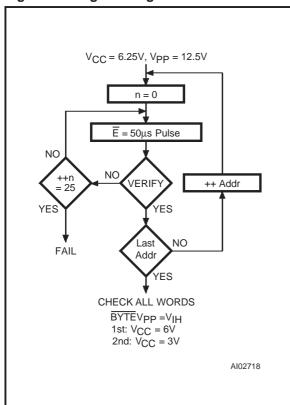


Figure 8. Programming and Verify Modes AC Waveforms

Figure 9. Programming Flowchart



PRESTO III Programming Algorithm

The PRESTO III Programming Algorithm allows the whole array to be programed with a guaranteed margin in a typical time of 52.5 seconds. Programming with PRESTO III consists of applying a sequence of 50µs program pulses to each word until a correct verify occurs (see Figure 9).

During programing and verify operation a MARGIN MODE circuit is automatically activated to guarantee that each cell is programed with enough margin. No overprogram pulse is applied since the verify in MARGIN MODE at Vcc much higher than 3.6V provides the neccessary margin to each programmed cell.

Program Inhibit

Programming of multiple M27V160s in parallel with different data is also easily accomplished. Except for \overline{E} , all like inputs including \overline{G} of the parallel M27V160 may be common. A TTL low level pulse applied to a M27V160's \overline{E} input and V_{PP} at 12.5V, will program that M27V160. A high level \overline{E} input inhibits the other M27V160s from being programmed.

Program Verify

A verify (read) should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with \overline{E} at V_{IH} and \overline{G} at V_{IL} , V_{PP} at 12.5V and V_{CC} at 6.25V.

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On-Board Programming

The M27V160 can be directly programmed in the application circuit. See the relevant Application Note AN620.

Electronic Signature

The Electronic Signature (ES) mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment to automatically match the device to be programmed with its corresponding programming algorithm. The ES mode is functional in the 25° C \pm 5° C ambient temperature range that is required when programming the M27V160. To activate the ES mode, the programming equipmentmust force 11.5Vto 12.5V on address line A9 of the M27V160, with VPP=VCC=5V.

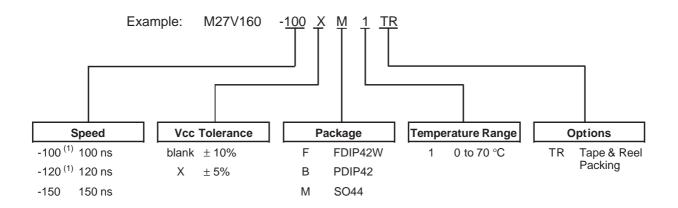
Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from V_{IL} to V_{IH} . All other address lines must be held at V_{IL} during Electronic Signature mode.

Byte 0 ($A0=V_{IL}$) represents the manufacturer code and byte 1 ($A0=V_{IH}$) the device identifier code. For the STMicroelectronics M27V160, these two identifier bytes are given in Table 4 and can be read-out on outputs Q0 to Q7. Note that the M27V160 and M27C160 have the same identifier bytes.

ERASURE OPERATION (applies to UV EPROM)

The erasure characteristics of the M27V160 is such that erasure begins when the cells are exposed to light with wavelengths shorter than approximately 4000 A. It should be noted that sunlight and some type of fluorescent lamps have wavelengths in the 3000-4000 Å range. Research shows that constant exposure to room level fluorescent lighting could erase a typical M27V160 in about 3 years, while it would take approximately 1 week to cause erasure when exposed to direct sunlight. If the M27V160 is to be exposed to these types of lighting conditions for extended periods of time, it is suggested that opaque labels be put over the M27V160 window to prevent unintentional erasure. The recommended erasure procedure for M27V160 is exposure to short wave ultraviolet light which has a wavelength of 2537 Å. The integrated dose (i.e. UV intensity x exposure time) for erasure should be a minimum of 30 W-sec/cm². The erasure time with this dosage is approximately 30 to 40 minutes using an ultraviolet lamp with 12000 $\mu W/cm^2$ power rating. The M27V160 should be placed within 2.5cm (1 inch) of the lamp tubes during the erasure. Some lamps have a filter on their tubes which should be removed before erasure.

ORDERING INFORMATION SCHEME

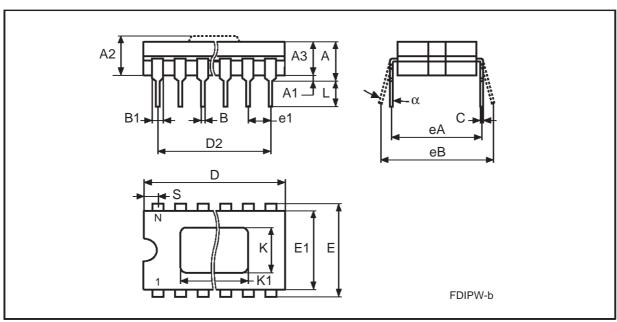


Note: 1. Speed obtained with High Speed measurement conditions.

 $For a\ list of\ available\ options\ (Speed, Package, etc...)\ or\ for\ further\ information\ on\ any\ aspect\ of\ this\ device,\ please\ contact\ the\ STM icroelectronics\ Sales\ Office\ nearest\ to\ you.$

FDIP42W - 42 pin Ceramic Frit-seal DIP, with window

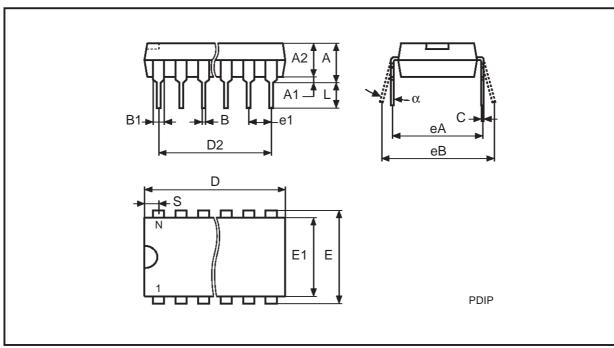
Symb		mm			inches	
Syllib	Тур	Min	Max	Тур	Min	Max
А		_	5.72		_	0.225
A1		0.51	1.40		0.020	0.055
A2		3.91	4.57		0.154	0.180
А3		3.89	4.50		0.153	0.177
В		0.41	0.56		0.016	0.022
B1	1.45	_	_	0.057	_	_
С		0.23	0.30		0.009	0.012
D		54.41	54.86		2.142	2.160
D2	50.80	_	_	2.000	_	_
E	15.24	_	_	0.600	_	_
E1		14.50	14.90		0.571	0.587
е	2.54	_	_	0.100	_	_
eA	14.99	_	_	0.590	_	_
eВ		16.18	18.03		0.637	0.710
L		3.18			0.125	
S		1.52	2.49		0.060	0.098
K	9.40	_	_	0.370	_	_
K1	11.43	_	_	0.450	_	_
α		4°	11°		4°	11°
N		42	•		42	-



Drawing is not to scale.

PDIP42 - 42 pin Plastic DIP, 600 mils body width

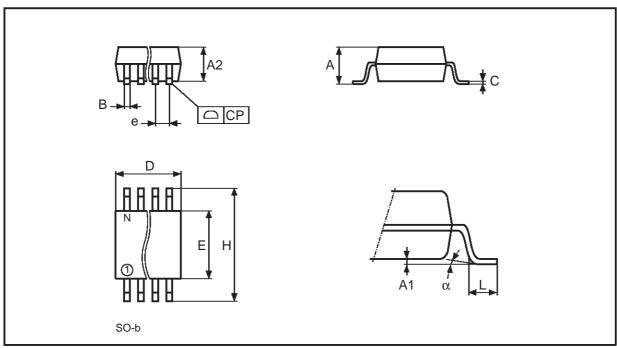
Symb		mm			inches	
Symb	Тур	Min	Max	Тур	Min	Max
А		_	5.08		_	0.200
A1		0.38	-		0.015	ı
A2		3.56	4.06		0.140	0.160
В		0.38	0.51		0.015	0.020
B1	1.52	_	_	0.060	_	-
С		0.20	0.30		0.008	0.012
D		54.48	54.74		2.145	2.155
D2	50.80	_	_	2.000	_	ı
E	15.24	_	_	0.600	_	-
E1		13.59	13.84		0.535	0.545
e1	2.54	_	-	0.100	_	ı
eA	15.24	_	-	0.600	_	ı
eB		15.24	17.78		0.600	0.700
L		3.18	3.43		0.125	0.135
S		1.78	2.03		0.070	0.080
α		0°	10°		0°	10°
N		42			42	



Drawing is not to scale.

SO44 - 44 lead Plastic Small Outline, 525 mils body width

Symb	mm			inches		
	Тур	Min	Max	Тур	Min	Max
А		2.42	2.62		0.095	0.103
A1		0.22	0.23		0.009	0.010
A2		2.25	2.35		0.089	0.093
В			0.50			0.020
С		0.10	0.25		0.004	0.010
D		28.10	28.30		1.106	1.114
E		13.20	13.40		0.520	0.528
е	1.27	_	-	0.050	-	-
Н		15.90	16.10		0.626	0.634
L	0.80	_	-	0.031	-	-
α	3°	-	-	3°	-	-
N	44			44		
СР			0.10			0.004



Drawing is not to scale.

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